502756687 04/07/2014

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT | |
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| NATURE OF CONVEYANCE: | ASSIGNMENT | |

CONVEYING PARTY DATA

| Name | Execution Date |
|--------------|----------------|
| KAZUKI HIRAI | 02/24/2014 |

RECEIVING PARTY DATA

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| City: GYODA-SHI, SAITAMA | | |
| State/Country: | JAPAN | |
| Postal Code: | 361-0037 | |

PROPERTY NUMBERS Total: 1

| Property Type | Number | |
|---------------------|----------|--|
| Application Number: | 14183776 | |

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| SIGNATURE: | /Catherine M. Voisinet/ | |
| DATE SIGNED: | 04/07/2014 | |

Total Attachments: 2

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PATENT 502756687 REEL: 032618 FRAME: 0248

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ASSIGNMENT

| Application N | o.: | .: 14/183, 776 | Fileda | FEB. 1 9. 2014 |
|------------------------------------|------|--|---|--|
| insert Name(s) of inventor(s) | ф | ***(Given Name FAMILY NAME (ALL CAPS) * WHEREAS, Kazuki HIRAI (hereinafter designated as the undersigned) I | | d certain new and useful improvements in: |
| insert Title of invention | ,e\$ | FLOW REGULATING DEVICE | | t s |
| | | for which an application for Letters Patent undersigned (except in the case of a provision | | ates of America has been executed by the |
| nsert Date of Signing of Apple. | => | ⇒ onFEB. 2.4. 2014 | | ; and |
| nsert Name of Assignee | Ø. | ⇒ WHEREAS, Surpass Industry Co., Ltd. | | |
| nsert Address of Assignee | 动 | ⇒ of 2203, Shimooshi, Gyoda-shi, Saitama 361-0 | 1037, Japan, | |
| | | its heirs, successors, legal representatives and of acquiring the entire right, title and interest that may be granted therefor in the United St | st in and to said in | vention and in and to any Letters Patent(s) |
| Check Box if Appropriate | 43 | in any foreign countries. | | |
| | | NOW, THEREFORE, for good and valuable the undersigned has (have) sold, assigned and transfer unto said Assignee the full and America, its territories, dependencies and poand all Letters Patent(s) which may be grar dependencies and possessions, and if the boarny and all divisions, reissues, continuation terms for which the same may be granted. | and transferred, as I exclusive right to essessions and the nted therefor in the x above is designate | nd by these presents does (do) sell, assign the said invention in the United States of entire right, title and interest in and to any the United States of America, its territories, ted, in any and all foreign countries; and to |

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The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of MH2 TECHNOLOGY LAW GROUP, LLP, the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

| Date | FEB. 2 4, 2014 | Name of Inventor | KQZUWHIYA) (Signature) Kazuki HIRAI | |
|------|----------------|------------------|-------------------------------------|--|
| Date | | Name of Inventor | | |
| Date | | Name of Inventor | (Signature) | |
| Date | | Name of Inventor | (Signature) | |
| Date | | Name of Inventor | (Signature) | |
| Date | | Name of Inventor | (Signature) | |
| | | | | |

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